

QF2060
No Clean Liquid Flux

Product Description

QF2060 is a no-clean, halide free RMA flux. It is specially designed to improve effectiveness in lead free wave soldering. QF2060 provides excellent solderability with reduction in micro-solderballing and solder bridging at connectors and QFP. The residue left behind is non-tacky, non-corrosive and non-conductive.

Application

QF2060 is specially formulated for spraying as well as foaming and dipping process. Recommended onboard preheat temperature is 80 – 120 °C (for heavy double sided board and boards running with pallet, the onboard preheat temperature may increase 10 – 20°C).

Residue Removal

Since the residues are minimal and non-corrosive, removal is usually not required. If cleaning is required, the flux residue could be removed by any solvent or aqueous flux cleaner available in the market.

Recommended Solvent

Thinning of flux is necessary if it is detected to have high specific gravity during the production. Asahi's complementary Solvent #2000 is recommended. Solvent can be stored for about 2 years under normal storage conditions of 25°C.

Health and Safety

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

Storage

Under proper storage condition, QF2060 can be stored for up to 6 months. QF2060 is flammable. Keep away from all sources of heat, sparks, flame and sunlight.

Packaging
DISCLAIMER OF LIABILITY
"All statements, information and recommendations contained in this catalog are based on data and test results which we consider, to the best of our knowledge and belief, to be reliable and informative to the users but the accuracy and completeness thereof is not guaranteed. No warranty, expressed or implied, statutory or otherwise, is given regarding the use of the information and products contained in this catalog since the conditions and suitability for use, handlings, storage or possession of the products are determined by the users and are therefore beyond our control. We shall not be liable in respect of any liabilities, losses (including consequential losses), damages, proceedings, costs, claims or injuries whatsoever sustained or suffered by the users (including any third parties) in connection with the use of the information, recommendation and the products contained in this catalog."
Specification

Item	Result
State	Liquid
Colour	Yellowish
Specific Gravity @ 25°C	0.810 +/- 0.005
<small>JIS Z 3197 8.2.2</small>	
Non-volatile Solid Content (110°C, 1hr)	6.8 +/- 0.5 wt%
<small>IPC-TM-650 2.3.34</small>	
<small>JIS Z 3197 8.1.3</small>	
Halide Content	Not added
<small>JIS Z 3197 8.1.4.2.1</small>	
Acid Value Test	27.5 +/- 2 mg KOH/g flux
<small>IPC-TM-650 2.3.13</small>	
<small>JIS Z 3197 8.1.4</small>	
Water Extract Resistivity	> 1 x 10 ⁴ Ω-cm
<small>JIS Z 3197 8.1.1</small>	
Surface Insulation Resistance (85°C, 85%RH, 168hrs)	> 1 x 10 ⁸ Ω, Pass
<small>IPC-TM-650 2.6.3.3</small>	
Electromigration (85°C, 88.5%RH, 596hrs)	Pass
<small>IPC-TM-650 2.6.14.1</small>	
Copper Corrosion Test	Pass
<small>IPC-TM-650 2.6.15</small>	
<small>JIS Z 3197 8.4.1</small>	
Copper Mirror Test	Classified as "M", Pass
<small>IPC-TM-650 2.3.32</small>	
<small>JIS Z 3197 8.4.2</small>	
Flux Activity Classification	ROM0
<small>IPC J-STD-004</small>	
Spread Factor	> 70% (SCS7)
<small>JIS Z 3197 8.3.1.1</small>	
Residue Dryness Test	Dry
<small>IPC-TM-650 2.4.47</small>	
<small>JIS Z 3197 8.5.1</small>	
Surface Finish	Shiny

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